AUTOMOTIVE

ROHS

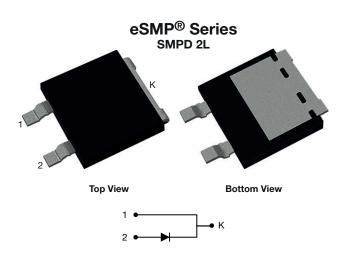
HALOGEN

FREE



### Vishay General Semiconductor

# **Surface-Mount ESD Capability Rectifiers**

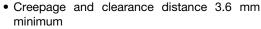


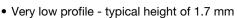
#### **LINKS TO ADDITIONAL RESOURCES**



PRIMARY CHARACTERISTICS					
I <sub>F(AV)</sub>	20 A				
V <sub>RRM</sub>	400 V, 600 V				
I <sub>FSM</sub>	150 A				
$V_F$ at $I_F = 20 \text{ A } (T_J = 125 ^{\circ}\text{C})$	1.03 V				
I <sub>R</sub>	25 μΑ				
T <sub>J</sub> max.	175 °C				
Package	SMPD 2L				
Circuit configurations	Single				

#### **FEATURES**





- Ideal for automated placement
- · Oxide planar chip junction
- Low forward voltage drop
- \_---
- ESD capability
- AEC-Q101 qualified available
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

#### TYPICAL APPLICATIONS

General purpose, power line polarity protection, in both consumer and automotive on board charger (OBC) applications.

#### **MECHANICAL DATA**

Case: SMPD 2L

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and industry

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test, HM3 suffix meets JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	SE20DTG	SE20DTJ	UNIT		
Device code		SE20DTG	SE20DTJ			
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	400	600	V		
Maximum DC forward current	I <sub>F</sub> <sup>(1)</sup>	20				
	I <sub>F</sub> <sup>(2)</sup>	3.8		_ A		
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	150				
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175				

#### Notes

<sup>(1)</sup> With heatsink

<sup>(2)</sup> Free air, mounted on recommended copper pad area



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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 10 A	T <sub>J</sub> = 25 °C		0.98	ī	V
	I <sub>F</sub> = 20 A		V <sub>E</sub> (1)	1.1	1.20	
	I <sub>F</sub> = 10 A	T <sub>J</sub> = 125 °C	VF (*)	0.88	-	
	I <sub>F</sub> = 20 A			1.03	1.15	
Reverse current	Rated V <sub>R</sub>	T <sub>J</sub> = 25 °C	=	25	μA	
	nateu v <sub>R</sub>	T <sub>J</sub> = 125 °C	IR (-)	38	150	μA
Typical reverse recovery time	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 0.25 A		t <sub>rr</sub>	3000	-	ns
Typical junction capacitance	4.0 V, 1 MHz		CJ	150	-	pF

#### Notes

(1) Pulse test: 300 µs pulse width, 1 % duty cycle

(2) Pulse test: Pulse width ≤ 40 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °c unless otherwise noted)					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Timical thermal variations	R <sub>θJA</sub> (1)(2)	60	75	°C/W	
Typical thermal resistance	R <sub>0</sub> JC (3)	1.2	1.5	C/VV	

#### Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$
- (2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
- (3) Thermal resistance junction-to-mount to follow JEDEC® 51-14 transient dual interface test method (TDIM)

IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS ( $T_A = 25~^{\circ}\text{C}$ unless otherwise noted)						
STANDARD	TEST TYPE	TEST CONDITIONS	SYMBOL	CLASS	VALUE	
AEC-Q101-001	Human body model (contact mode)	C = 100 pF, R = 1.5 kΩ	$V_{C}$	НЗВ	> 8 kV	

ORDERING INFORMATION (Example)						
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE		
SE20DTJ-M3/I	0.52	I	2000 / reel	13" diameter plastic tape and reel		
SE20DTJHM3/I (1)	0.52	1	2000 / reel	13" diameter plastic tape and reel		

#### Note

(1) AEC-Q101 qualified



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### **RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25$ °C unless otherwise noted)

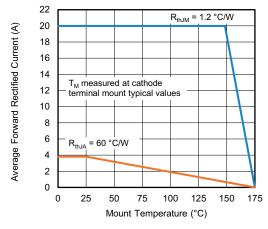


Fig. 1 - Forward Current Derating Curve

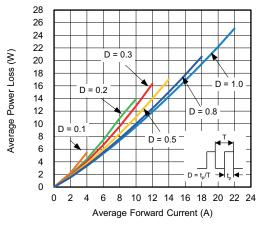


Fig. 2 - Forward Power Loss Characteristics

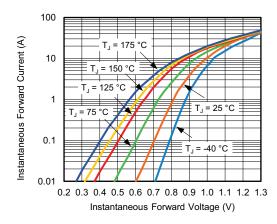


Fig. 3 - Typical Instantaneous Forward Characteristics

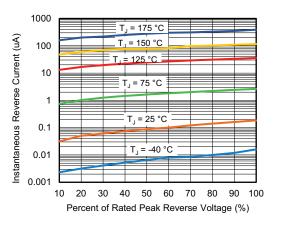


Fig. 4 - Typical Reverse Leakage Characteristics

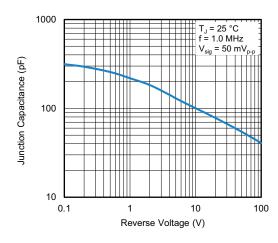


Fig. 5 - Typical Junction Capacitance

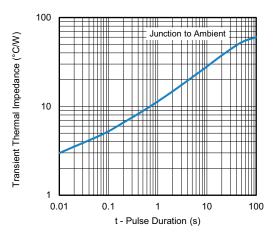


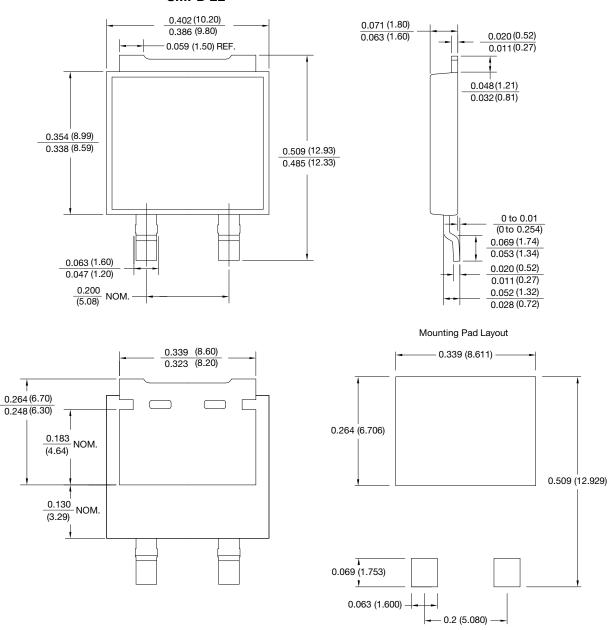
Fig. 6 - Typical Transient Thermal Impedance



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### PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

#### SMPD 2L



#### Note

• The suggested mounting pad layout is provided for reference only, as actual pad layouts may vary depending on application



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